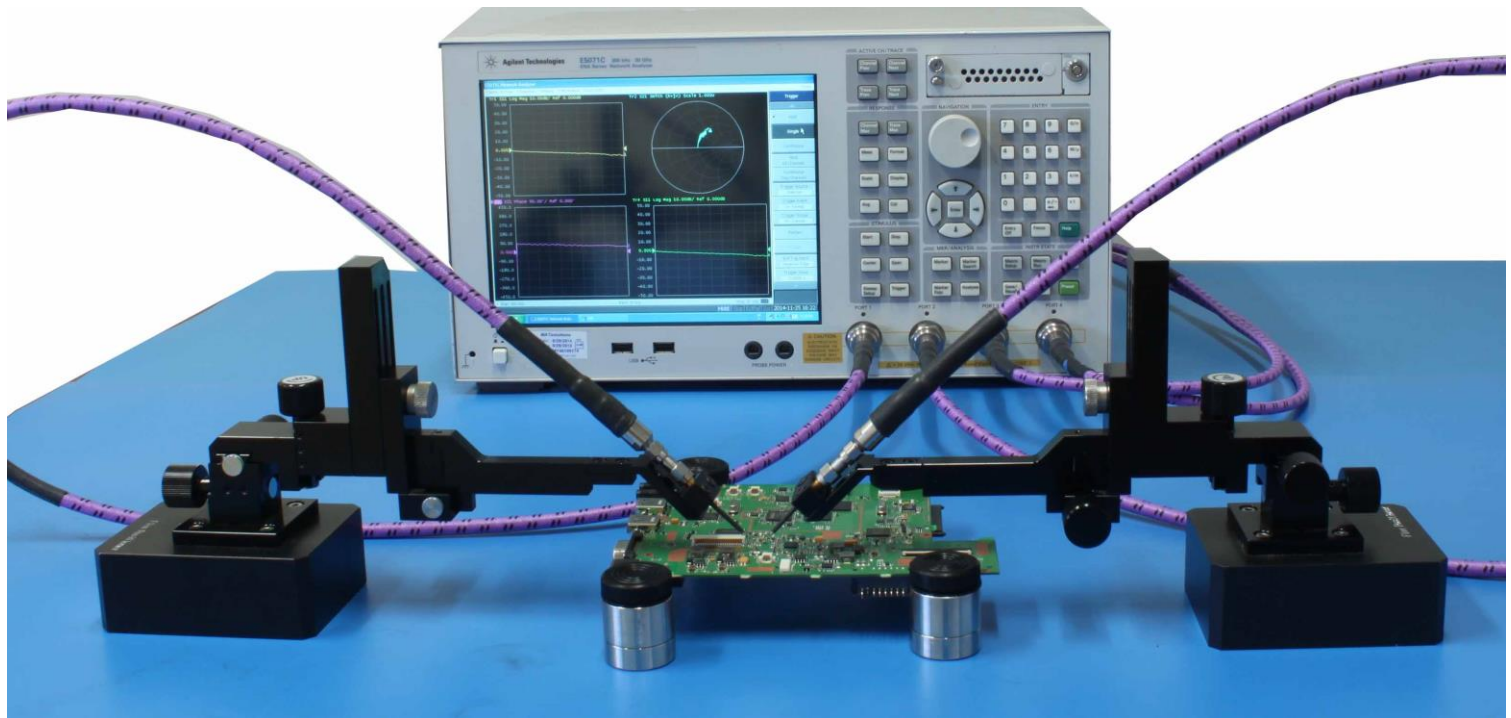
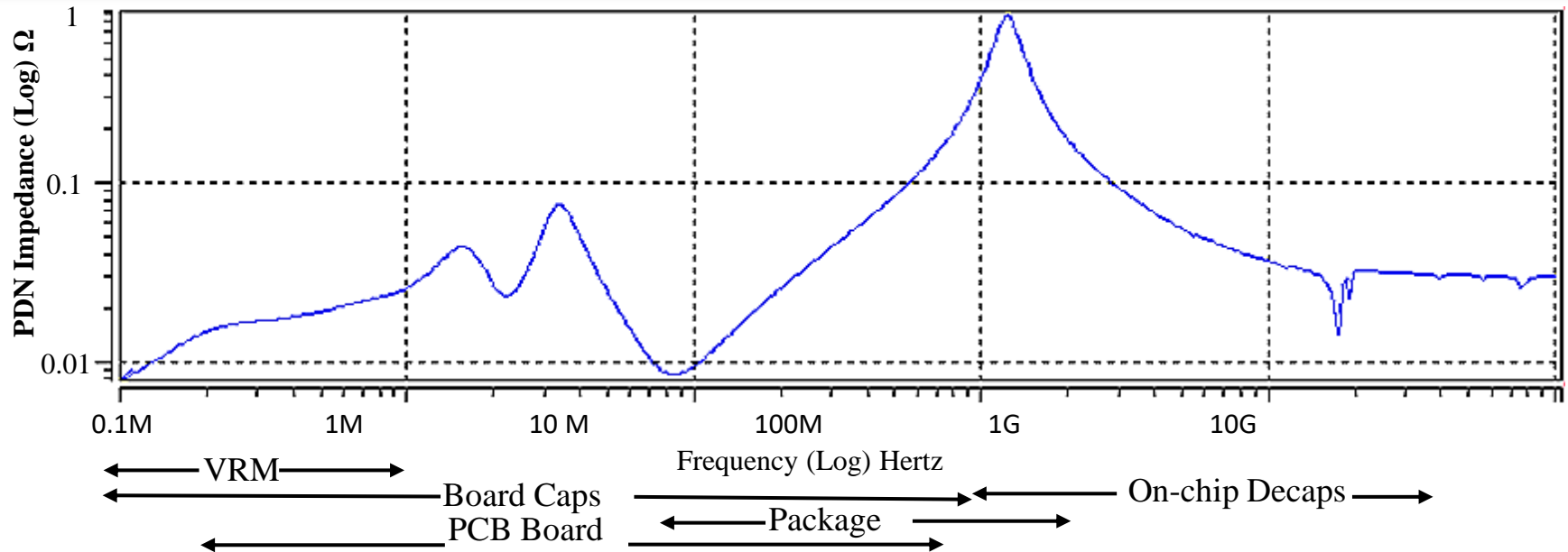


# Power Integrity Measurement With Keysight VNA

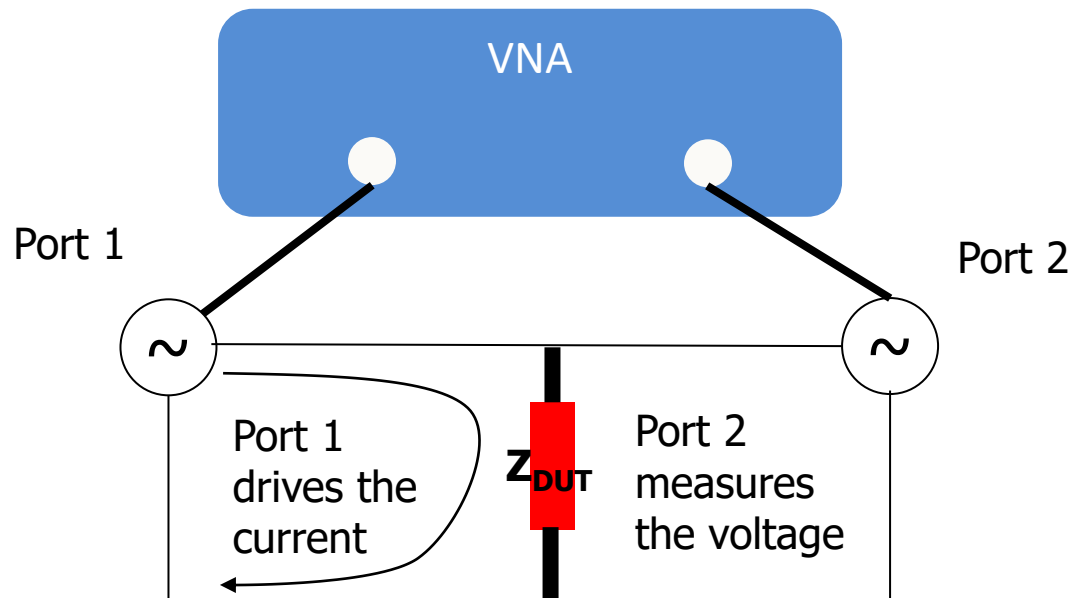


# Typical PDN Impedance Profile



- Impedance profile formed by the interaction of various PDN components
- Impedance peak at package/chip resonance
- Peak impedance dependent on package, PCB, and on-chip parameters
- Typical impedance in the range of tens of milliohms

# 2-Port VNA Measurements of Low $Z_{DUT}$



- 1<sup>st</sup> order Analysis

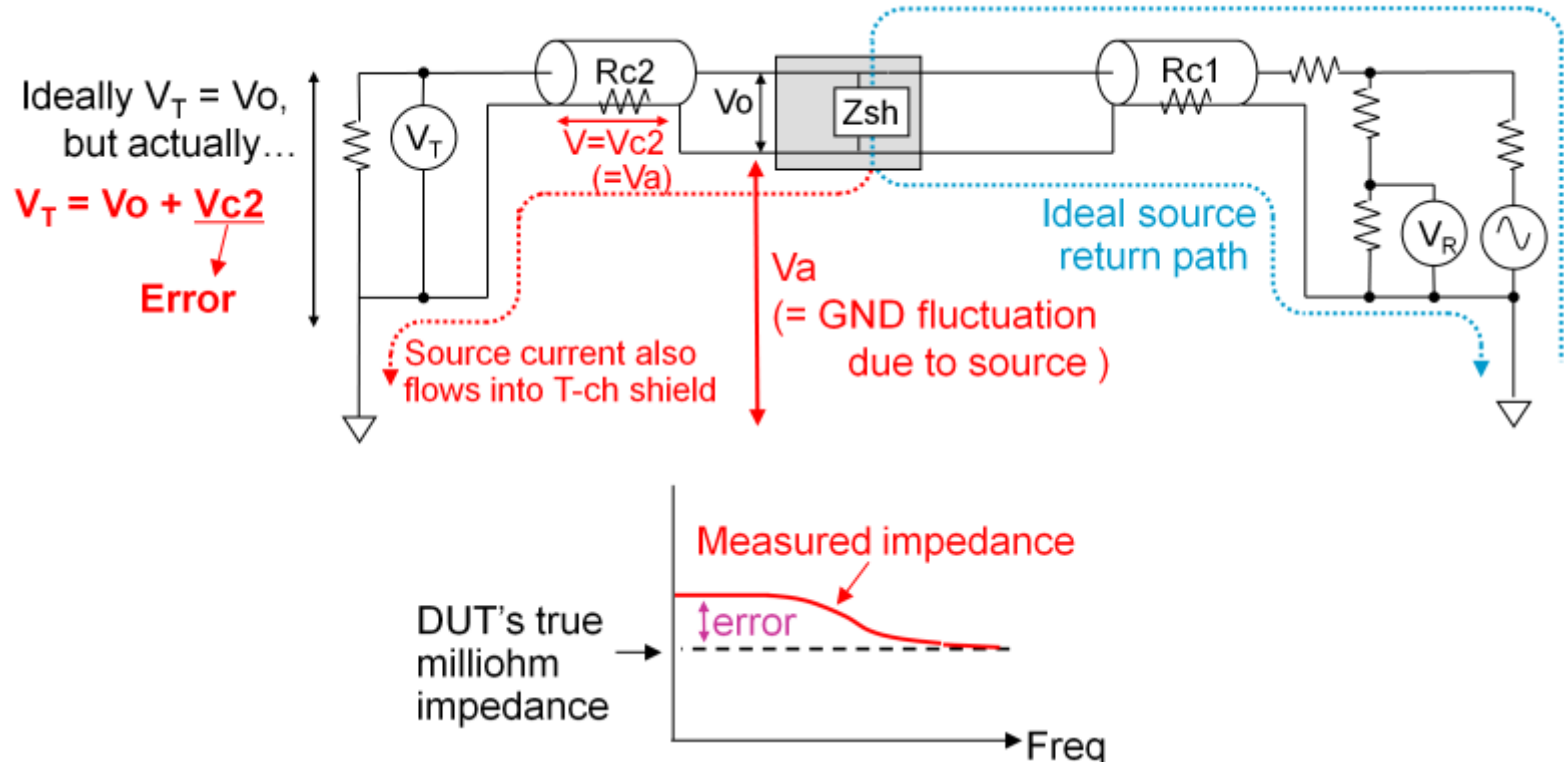
$$(Z_{DUT} \ll Z_o)$$

$$Z_{DUT} = 25 S_{21} \Omega$$

- 2<sup>nd</sup> order Analysis

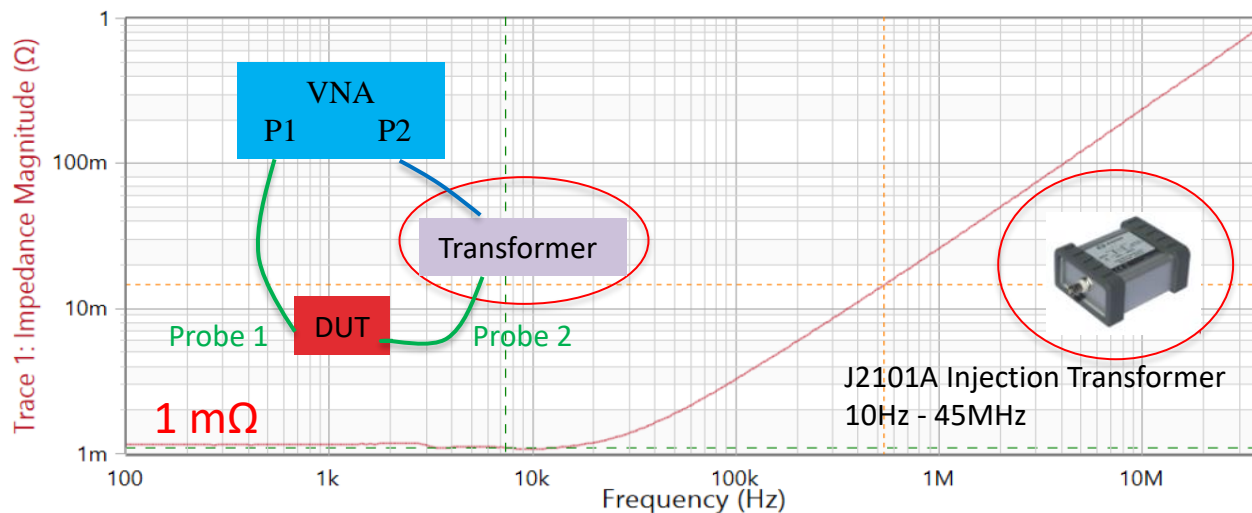
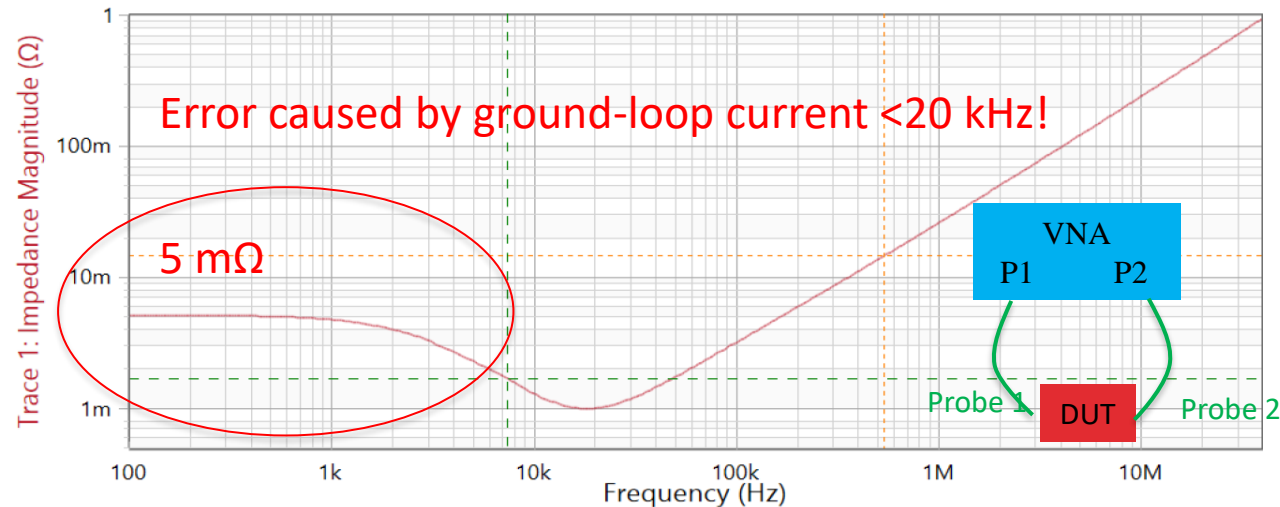
$$Z_{DUT} = 25 \frac{S_{21}}{1 - S_{21}} \Omega$$

# Low-Freq Errors Caused by Ground Loop

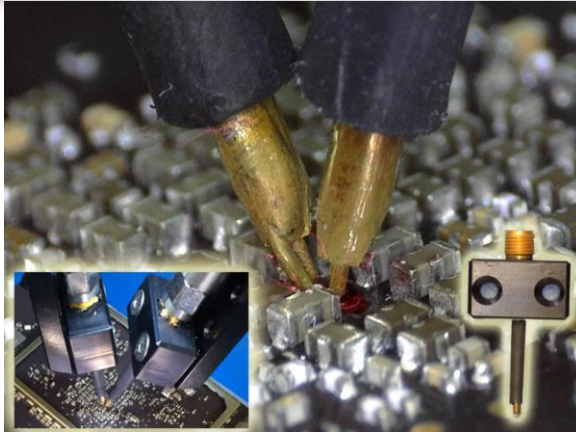


If the DUT's impedance is very small ( $Z_{DUT} < \text{tens of milliohms}$ )  
**Source current flows into source-to-receiver cable GND loop.**  
**Measurement errors occur at LF range (<20kHz)**

# Use Transformer to Break the Ground Loop

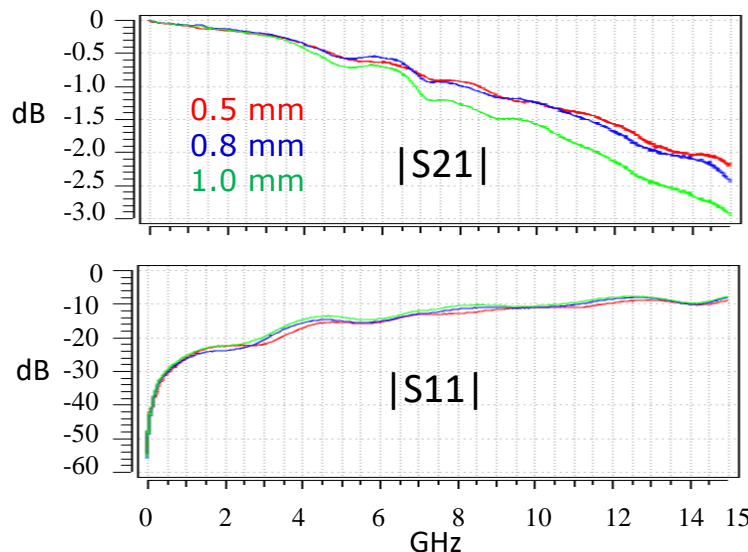
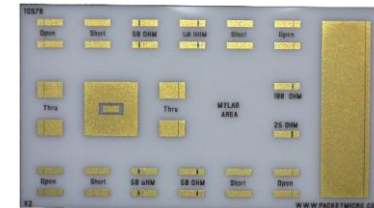


# 18 GHz R-Probe



**R-Probe** is ideal for probing a populated board with test points surrounded by components because of its 30-mil probe tips. Typical R-Probe applications are PDN and RF measurements.

## TCS70 Calibration Substrate



## Specifications:

**Substrate:** Polished alumina

**Structure:** Open, short, thru, 25  $\Omega$ , 50  $\Omega$ , 100  $\Omega$

**Contact Material:** Gold

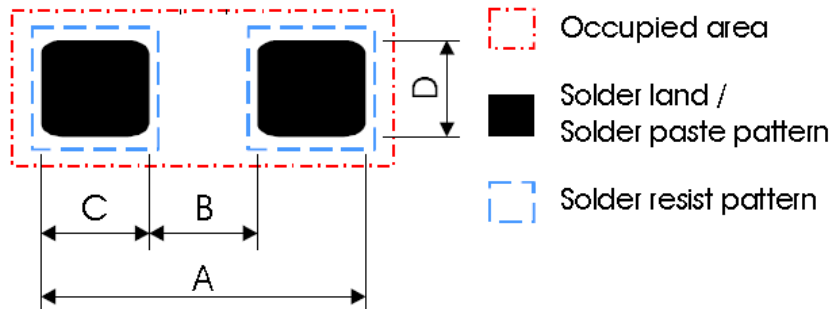
**Accuracy:** 25  $\Omega$ , 50  $\Omega$  < 0.5%, 100  $\Omega$  < 1%

**Size:** 17.3 x 9.4 x 0.6 mm (0.68 x 0.37 x 0.025 in)

## R-Probe Part No.

- **RP-GR-151502** – 18 GHz, 0.2 mm/ 8 mil pitch
- **RP-GR-151503** – 18 GHz, 0.3 mm/ 8 mil pitch
- **RP-GR-151504** – 15 GHz, 0.4 mm/16 mil pitch
- **RP-GR-151505** – 15 GHz, 0.5 mm/20 mil pitch
- **RP-GR-121508** – 12 GHz, 0.8 mm/32 mil pitch
- **RP-GR-121510** – 12 GHz, 1.0 mm/40 mil pitch

# Probe-Pitch Selection



## R-Probe Part Number:

- **RP-GR-181502** - 18 GHz, 0.2 mm/ 8 mil pitch
- **RP-GR-181503** - 18 GHz, 0.3 mm/ 12 mil pitch
- **RP-GR-151504** - 15 GHz, 0.4 mm/ 16 mil pitch
- **RP-GR-151505** - 15 GHz, 0.5 mm/ 20 mil pitch
- **RP-GR-121508** - 12 GHz, 0.8 mm/ 32 mil pitch
- **RP-GR-121510** - 12 GHz, 1.0 mm/ 40 mil pitch

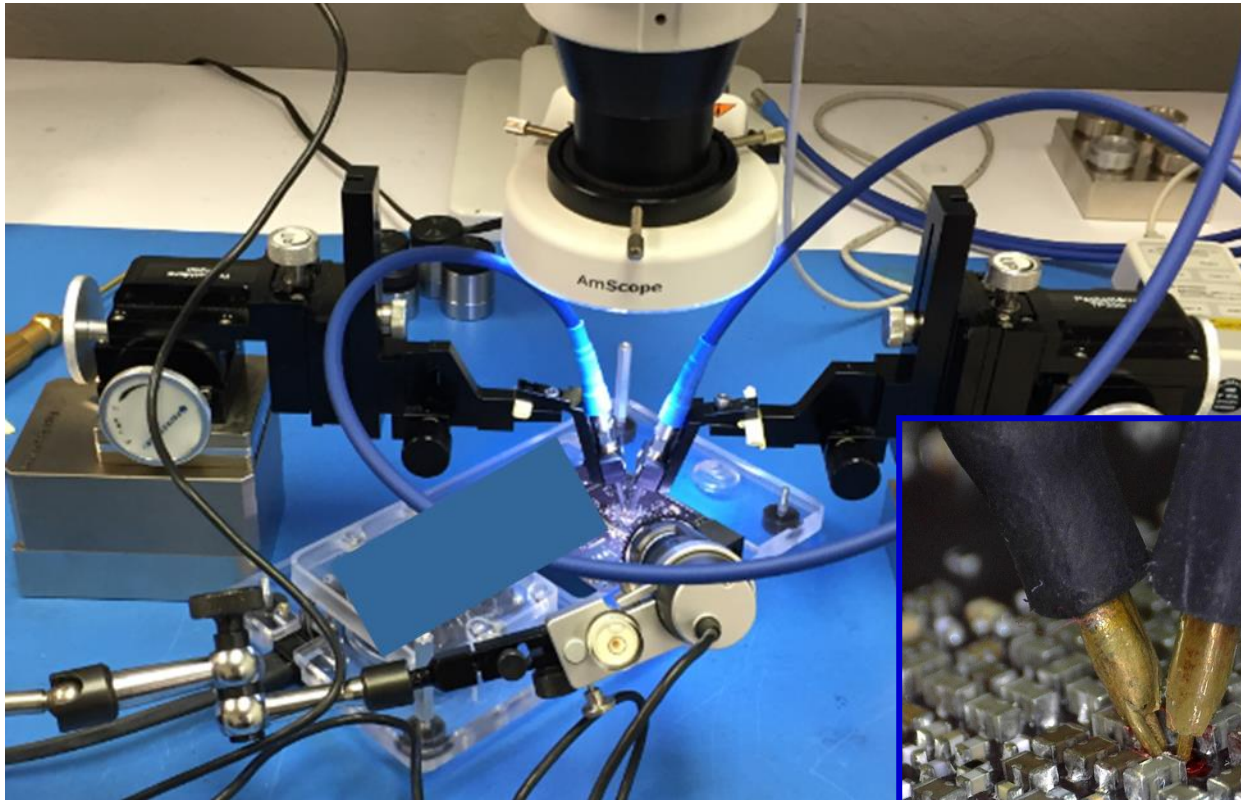
**Recommendation:  $B + 0.2 \text{ mm} < \text{Probe Pitch} < A - 0.2 \text{ mm}$**

Size	Probe Pitch	A	B	C	D	Component Size
01005	RP-GR-181503	0.48	0.12	0.18	0.20	0.4 x 0.2
0201	RP-GR-151505	0.75	0.30	0.30	0.30	0.6 x 0.3
0402	0.7mm < Pitch < 1.3mm	1.50	0.50	0.50	0.60	1.0 x 0.5
0603	0.8mm < Pitch < 1.9mm	2.10	0.60	0.90	0.90	1.6 x 0.8
0805	1.2mm < Pitch < 2.8mm	3.0	1.0	1.0	1.25	2.0 x 1.25

Typical Reflow Soldering Footprint and Component Size in mm



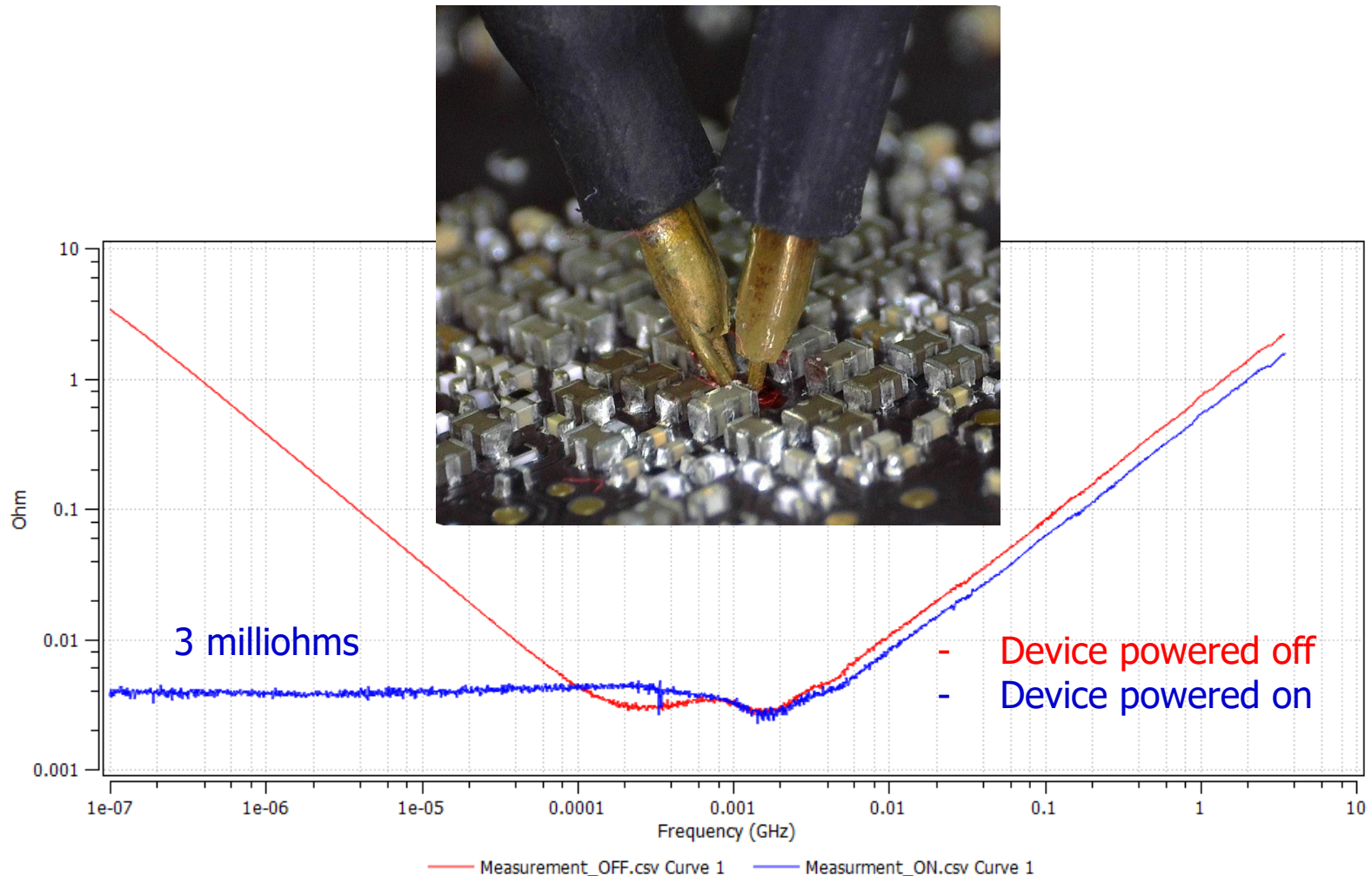
# Power Integrity Probing



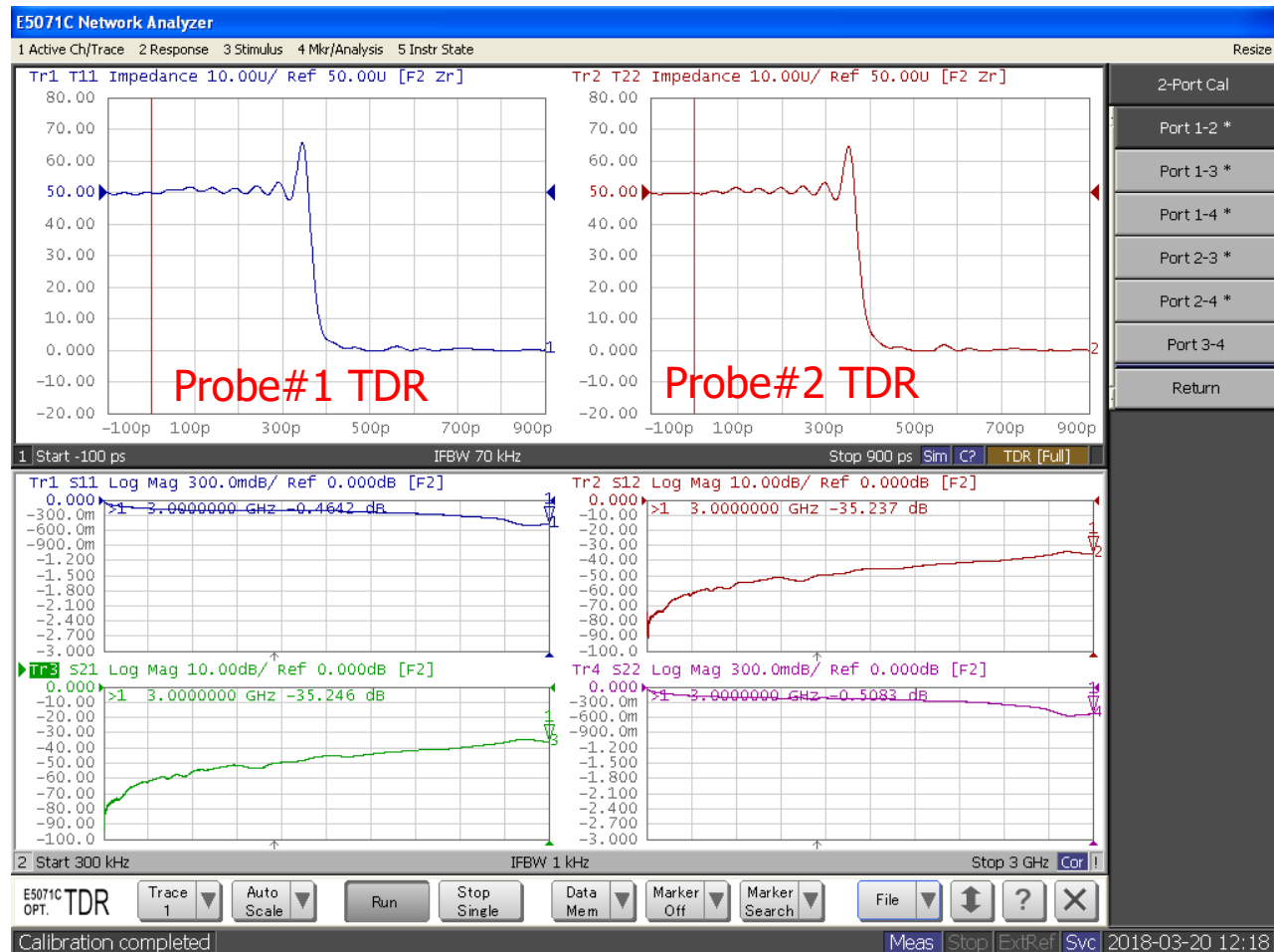
- PI Probing amid surrounding components is challenging



# Milliohm PDN Measurements



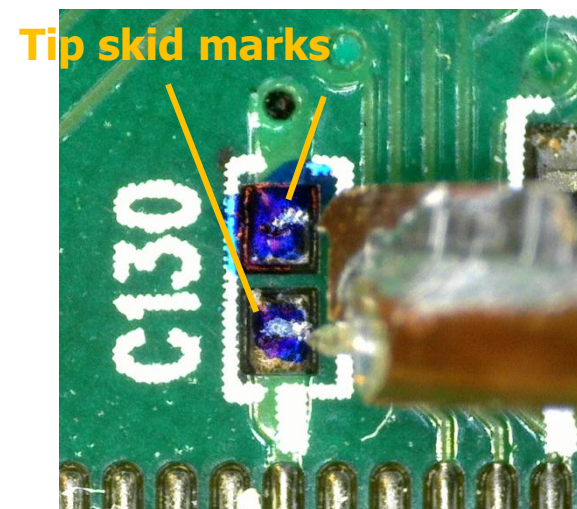
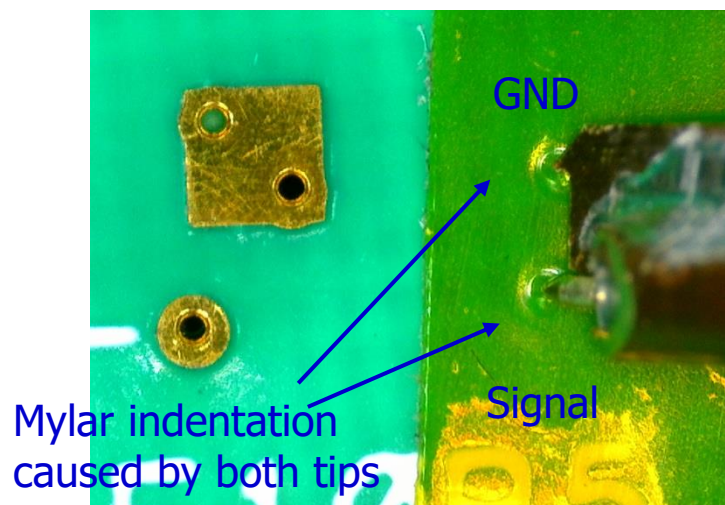
# PDN Measurement with E5071C VNA



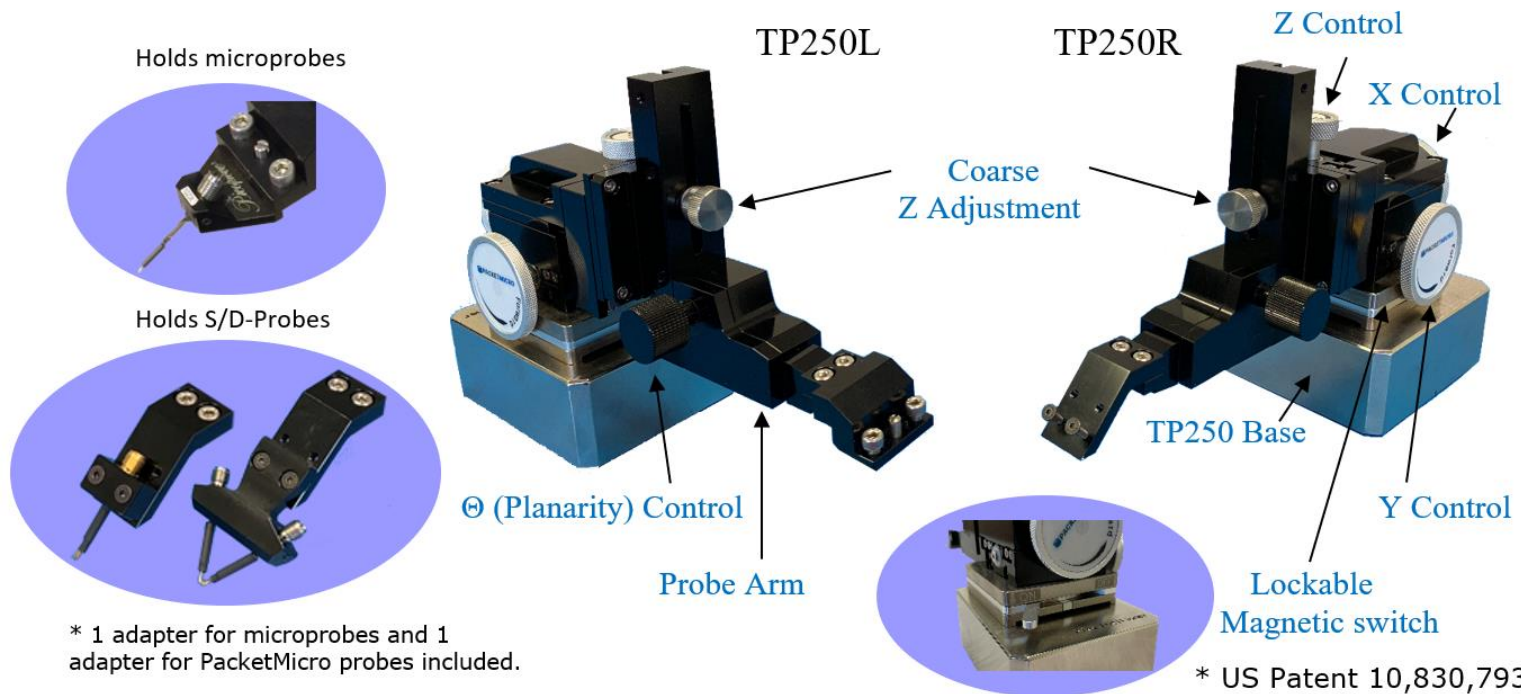
Use TDR channel to ensure good probe-tip contact!

# Probe Planarization Tips

- Good contact of both probe tips with the DUT is essential to accurate calibration and measurements.
- Mylar tape provides leveling guidance on flat, even surface (bare PCB).
- Color marker helps on uneven surface (solder bump).
- A good microscope is important. You might damage the probe if you cannot see its tips well.



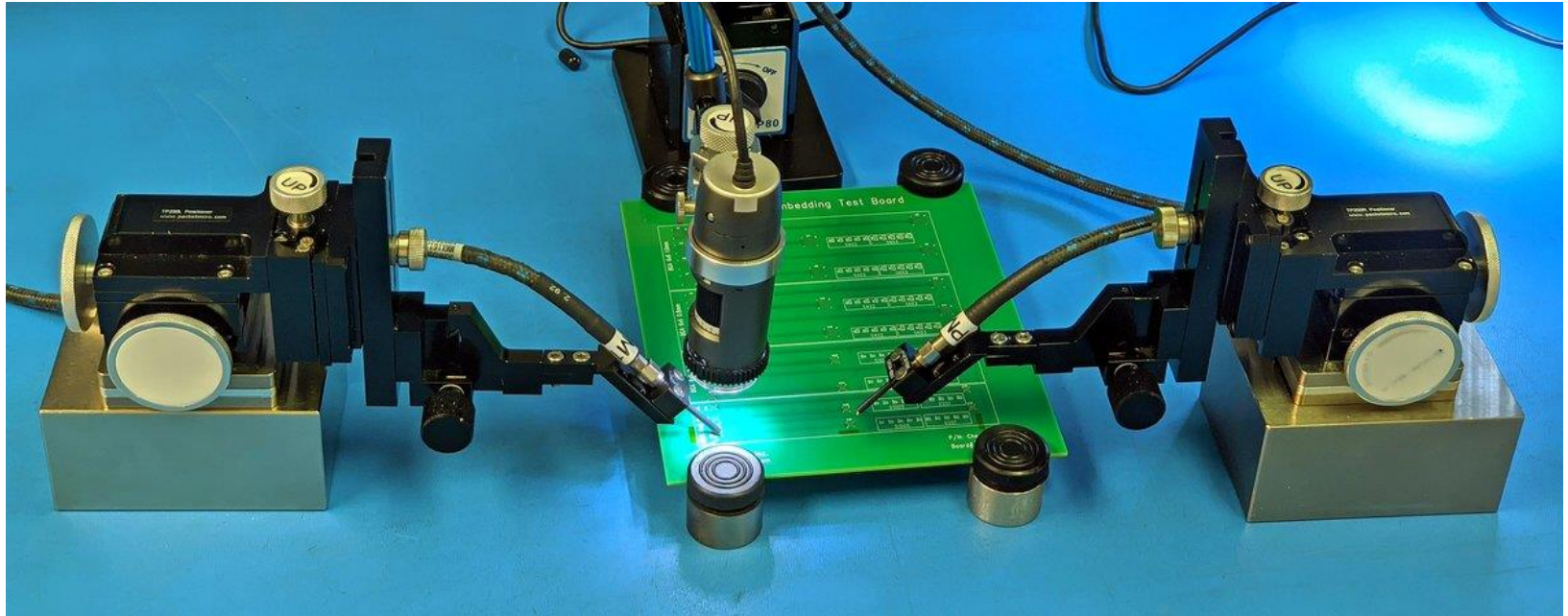
# TP250 Precision Positioner



- **XYZ-axis travel:** 16 mm with 500  $\mu\text{m}/\text{turn}$  (50 TPI, 5 $\mu\text{m}$  resolution)
- **Height coarse adjustment:** 5 mm/step (14 steps)
- **$\Theta$  (Planarity) control:**  $\pm 10^\circ$  with 2.5 $^\circ$  /turn and 0.025 $^\circ$  resolution
- **Dimension:** 9" L x 2.7" W x 4.3" H
- **Weight:** 2.86 lb./1.30 kg



# Probe Planarization with TP250

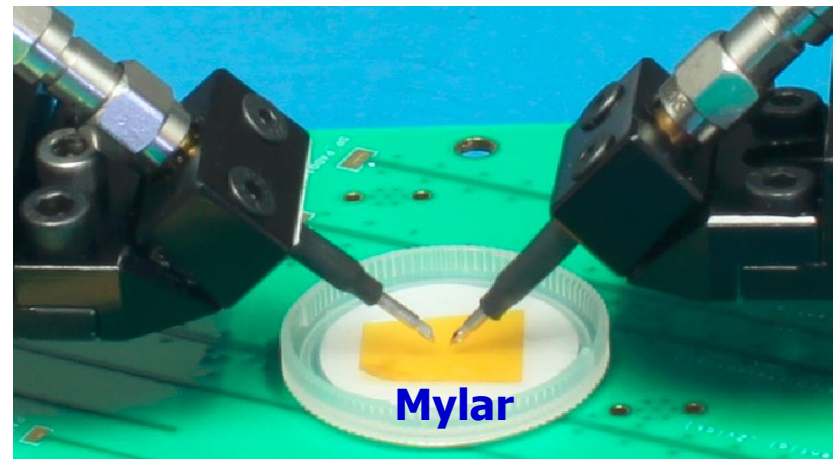
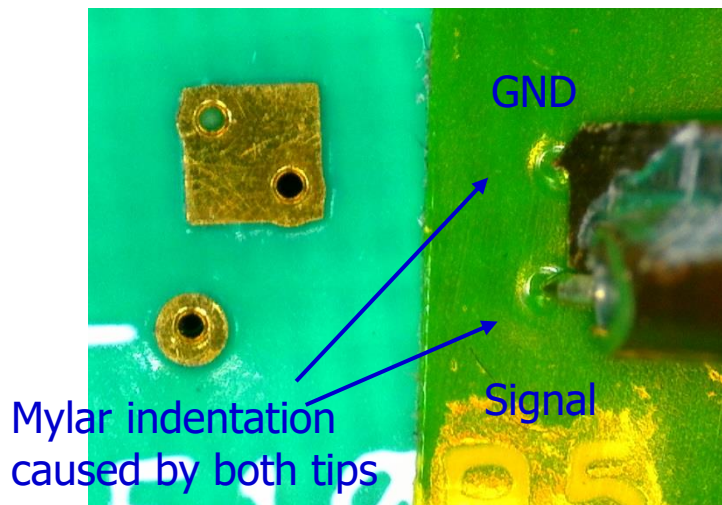


**Probe Planarization Video:**

[https://packetmicro.com/Videos/PacketMicro\\_Probe\\_Planarization.mp4](https://packetmicro.com/Videos/PacketMicro_Probe_Planarization.mp4)

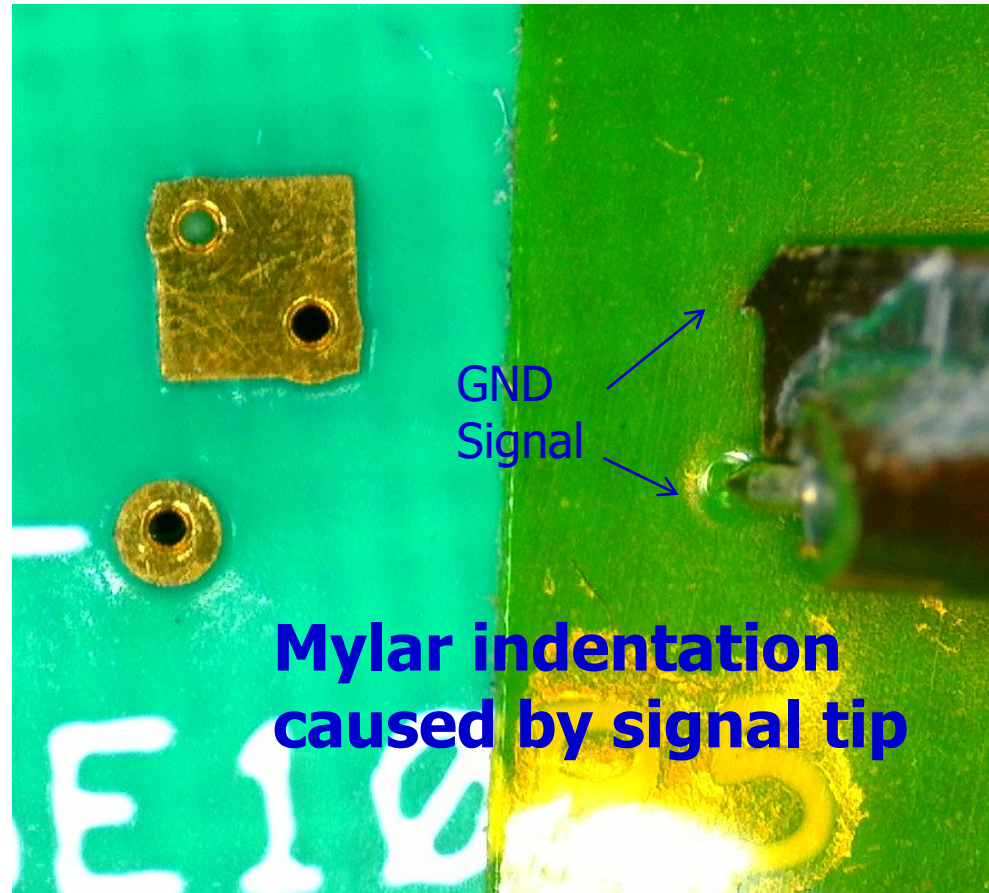
# Probe Planarization on Even Surface

- Use the Mylar tape on the back of the plastic cap for probe planarization by observing the indentation caused by the tips.
- Remove the plastic cap and perform probing
- Affix a Mylar tape next to test pads if there is not enough space for placing the plastic cap.





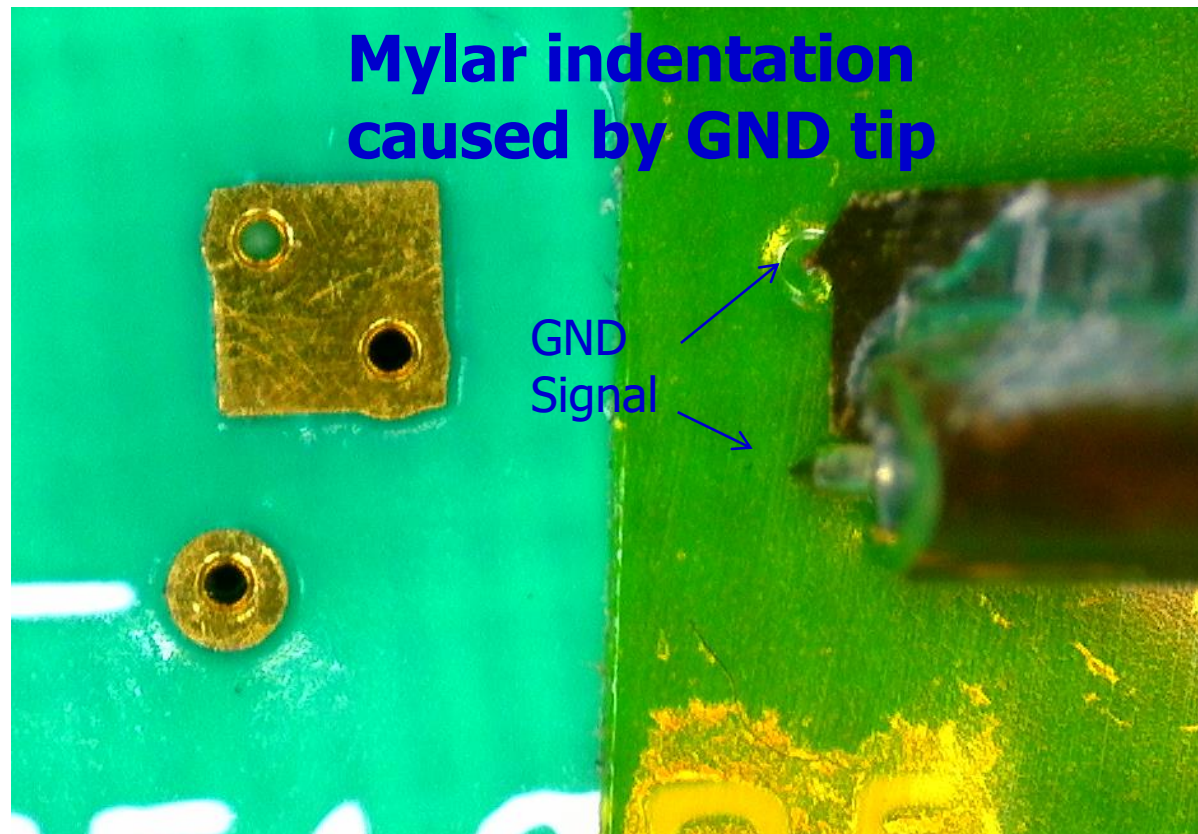
# Signal tip touches down first



## Step 1:

Land the probe tips on the tape and observe the probe-tip footprint. Above image shows that signal tip touches the surface first.

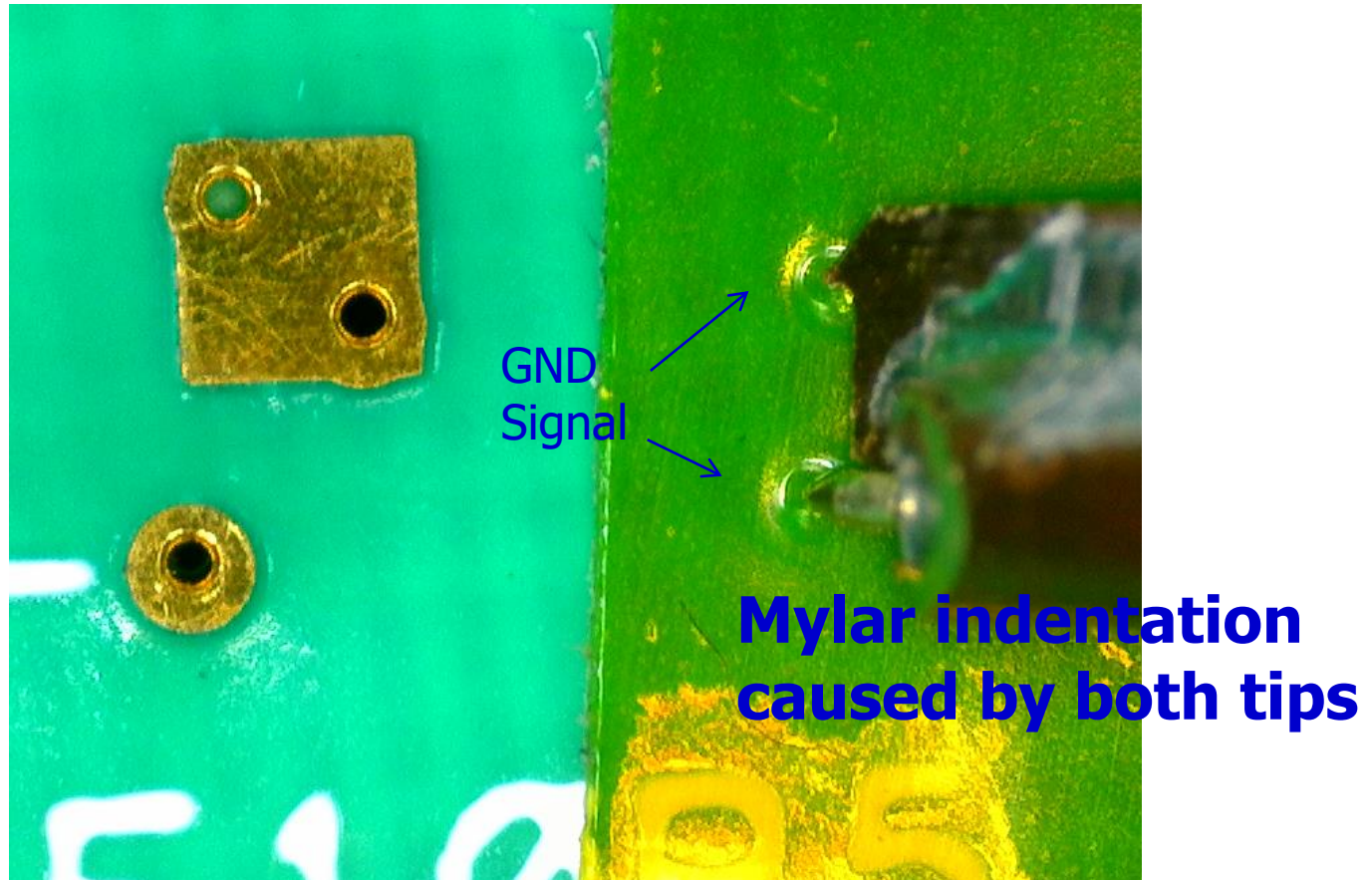
# GND tip touches down first



## Step 2:

Adjust the planarization knob on the TP150 positioner to lower the GND tip. Above image shows that GND tip touches the surface first.

# Both tips touch down simultaneously



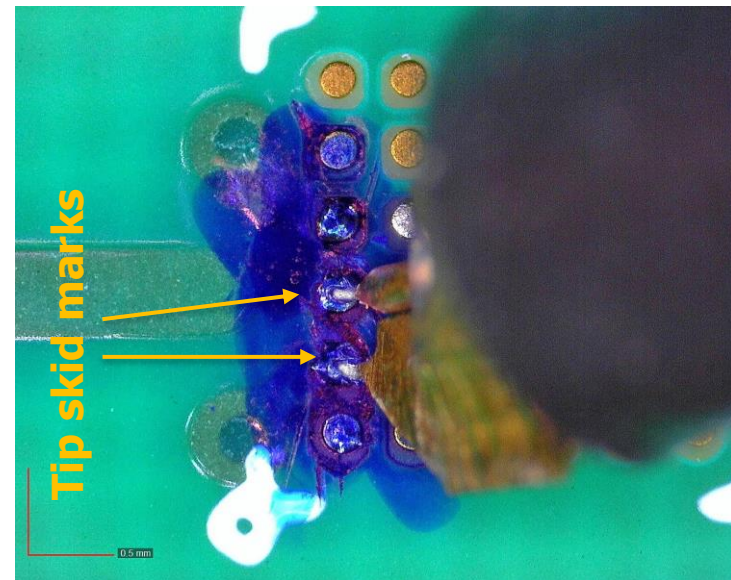
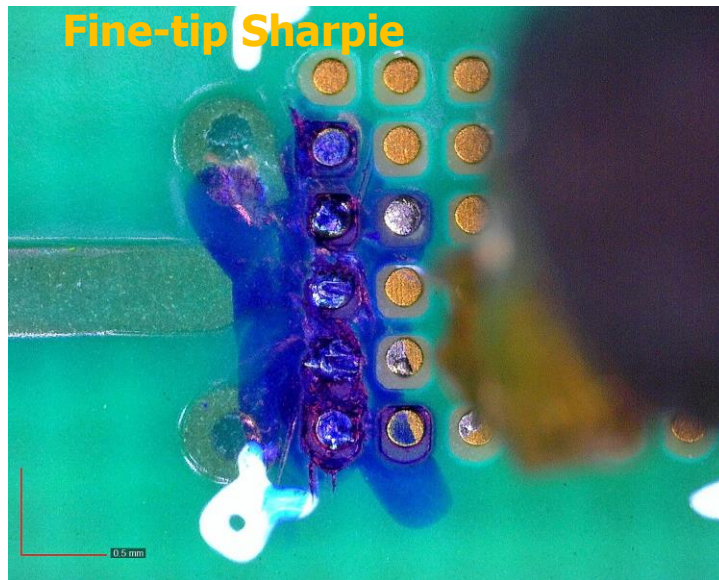
## Step 3:

Adjust the planarization knob on the positioner to land both probe tips. Above image shows the two probe tips touch the surface evenly.

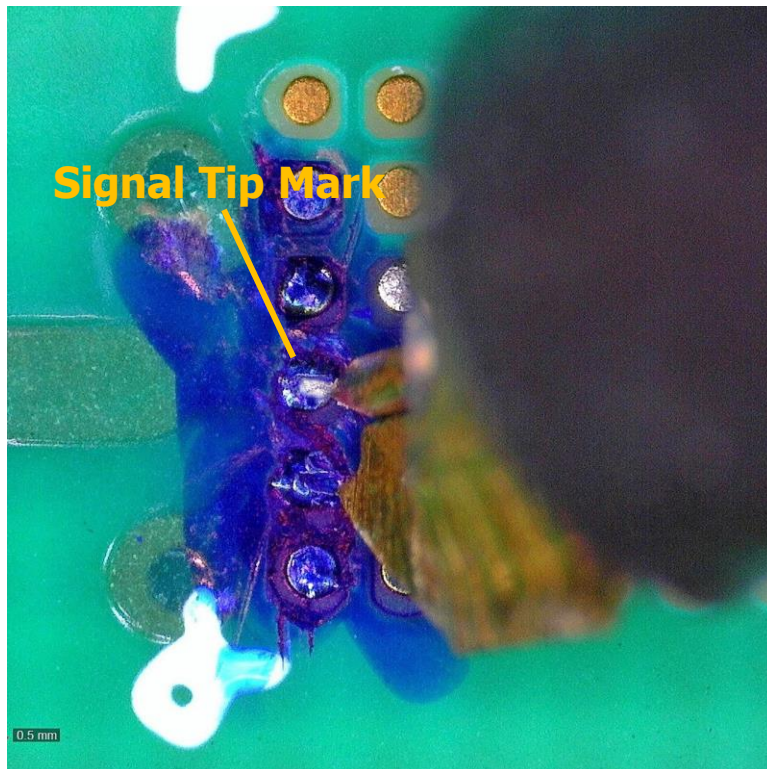


# Land Probe Tips on Solder Bumps

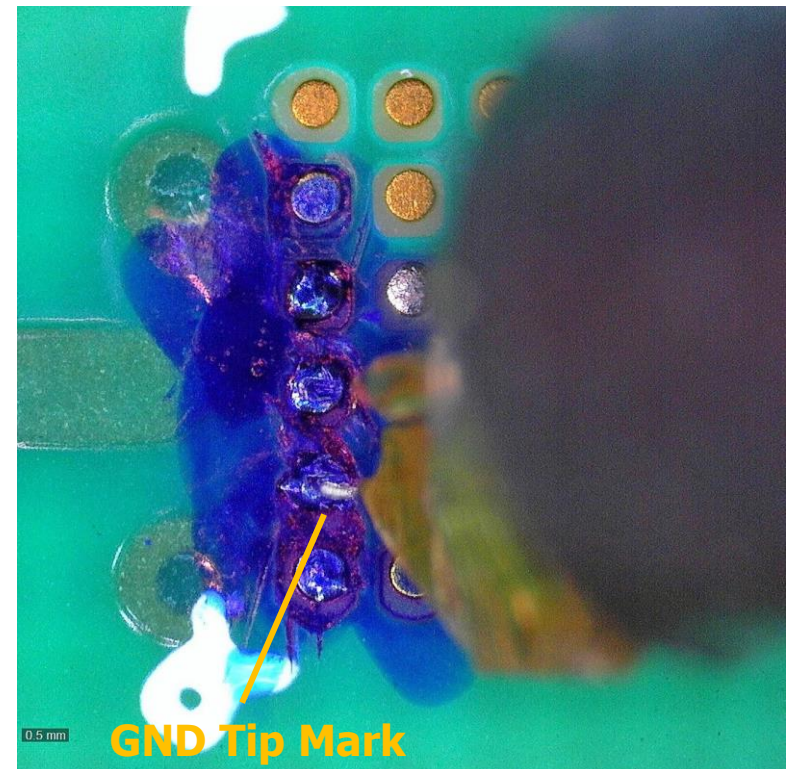
- Color solder bumps with a Sharpie
- Use the probe skid marks to confirm good tip contact
- Clean up the solder bumps with industrial alcohol after probing



# Use Probe Skid Marks as Guidance



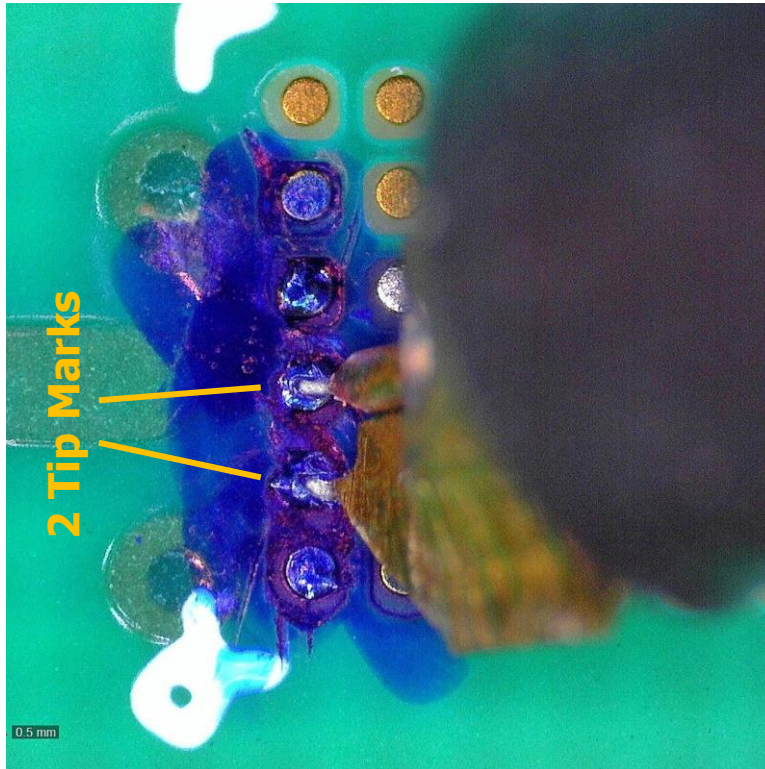
Top signal tip touches down first



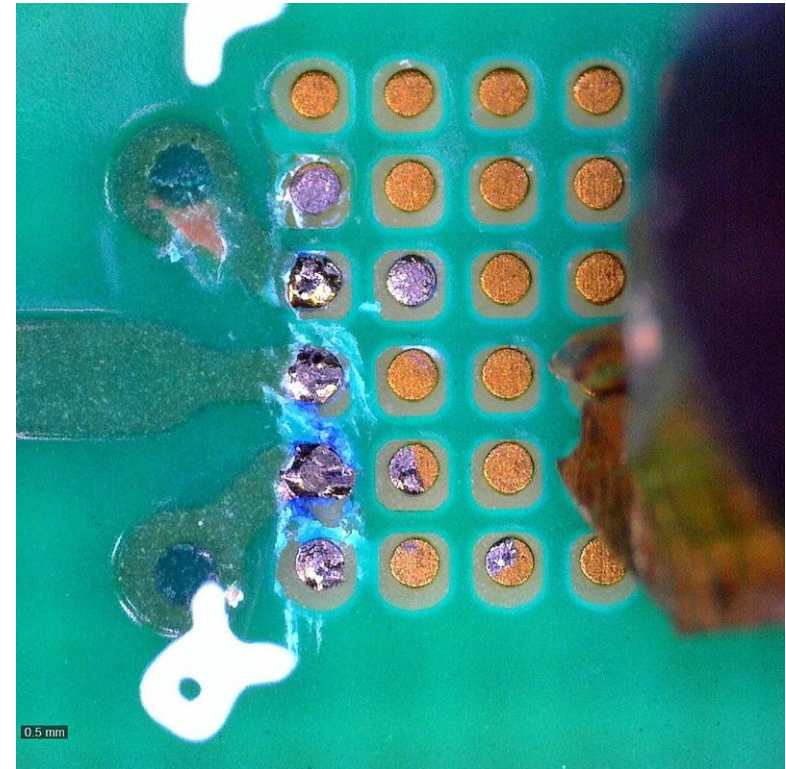
Bottom GND tip touches down first



# Both Tips Touch Down Simultaneously



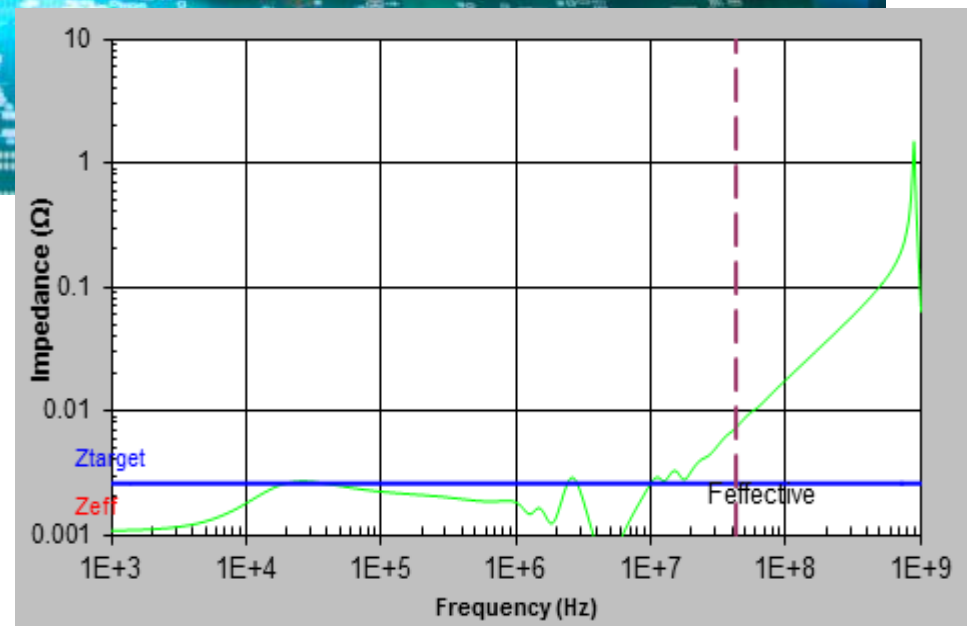
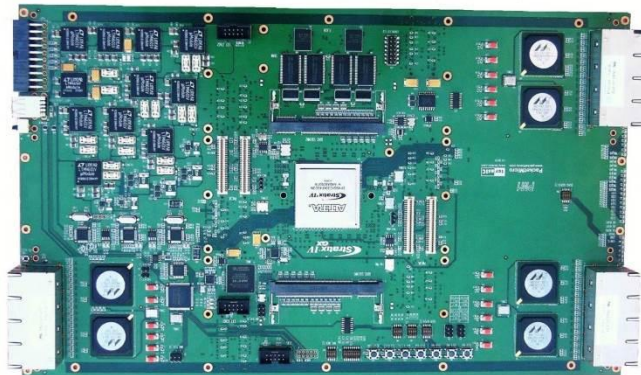
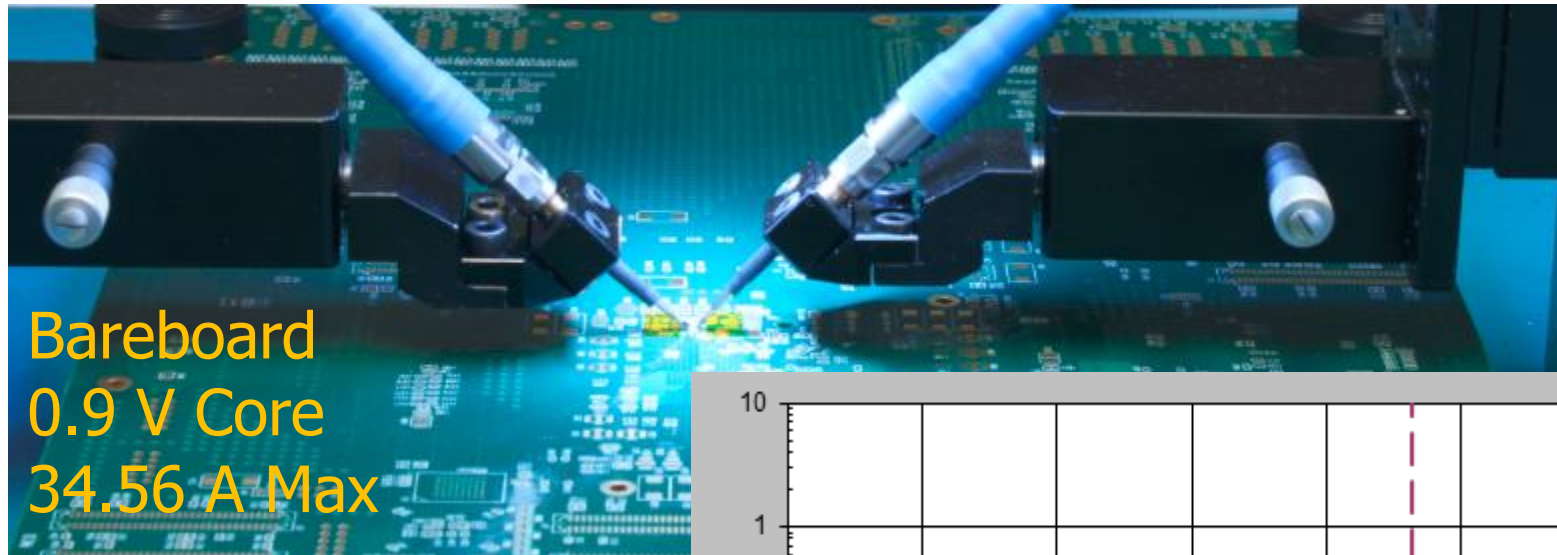
Both tips touch down simultaneously



Clean up solder bumps with industrial alcohol after probing



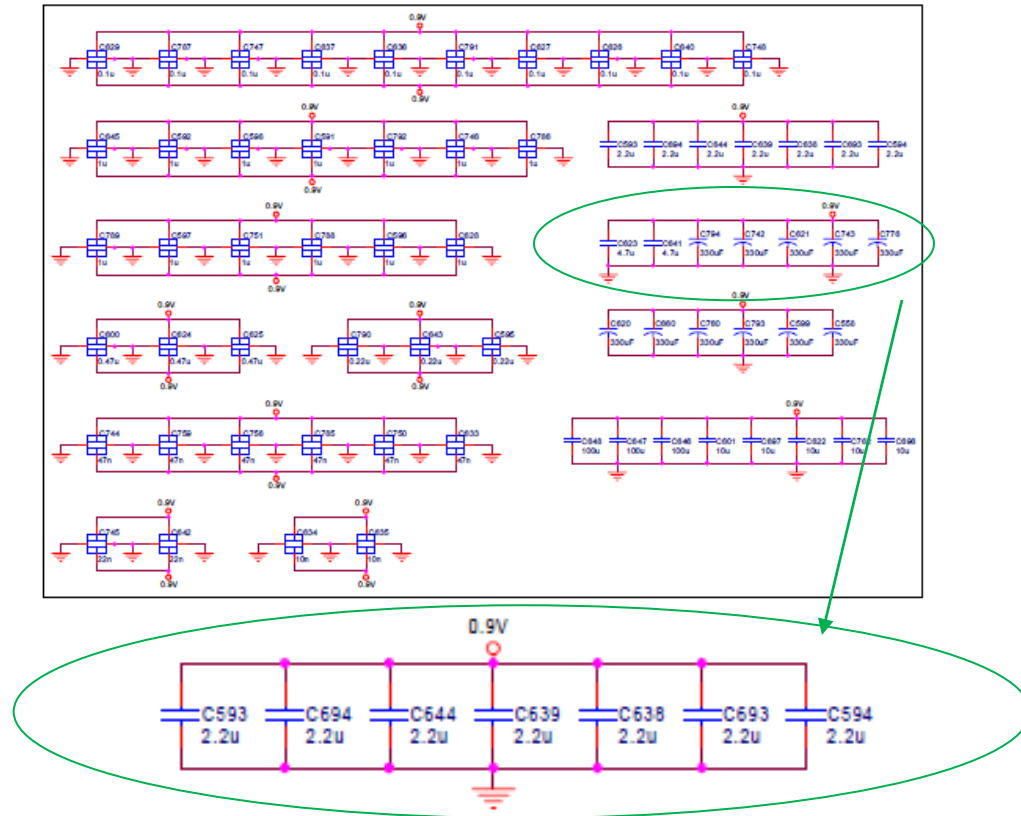
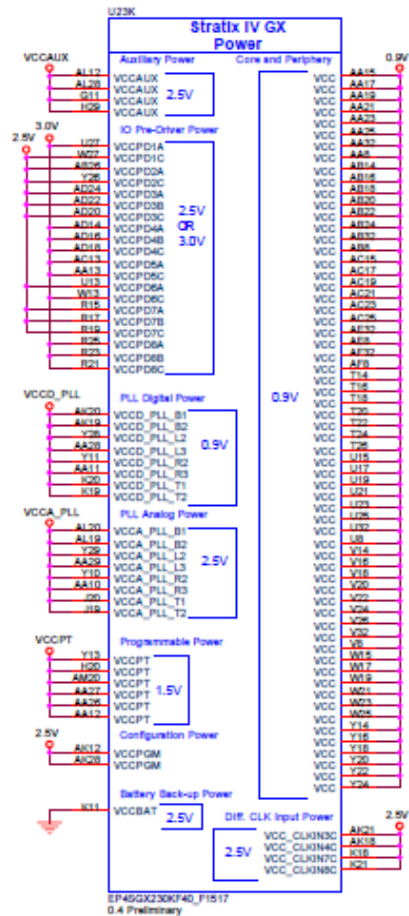
# 22-Layer Stratix III Test Board



22-layer Stratix III board

PDN Impedance Requirement

# PI Probing Demo

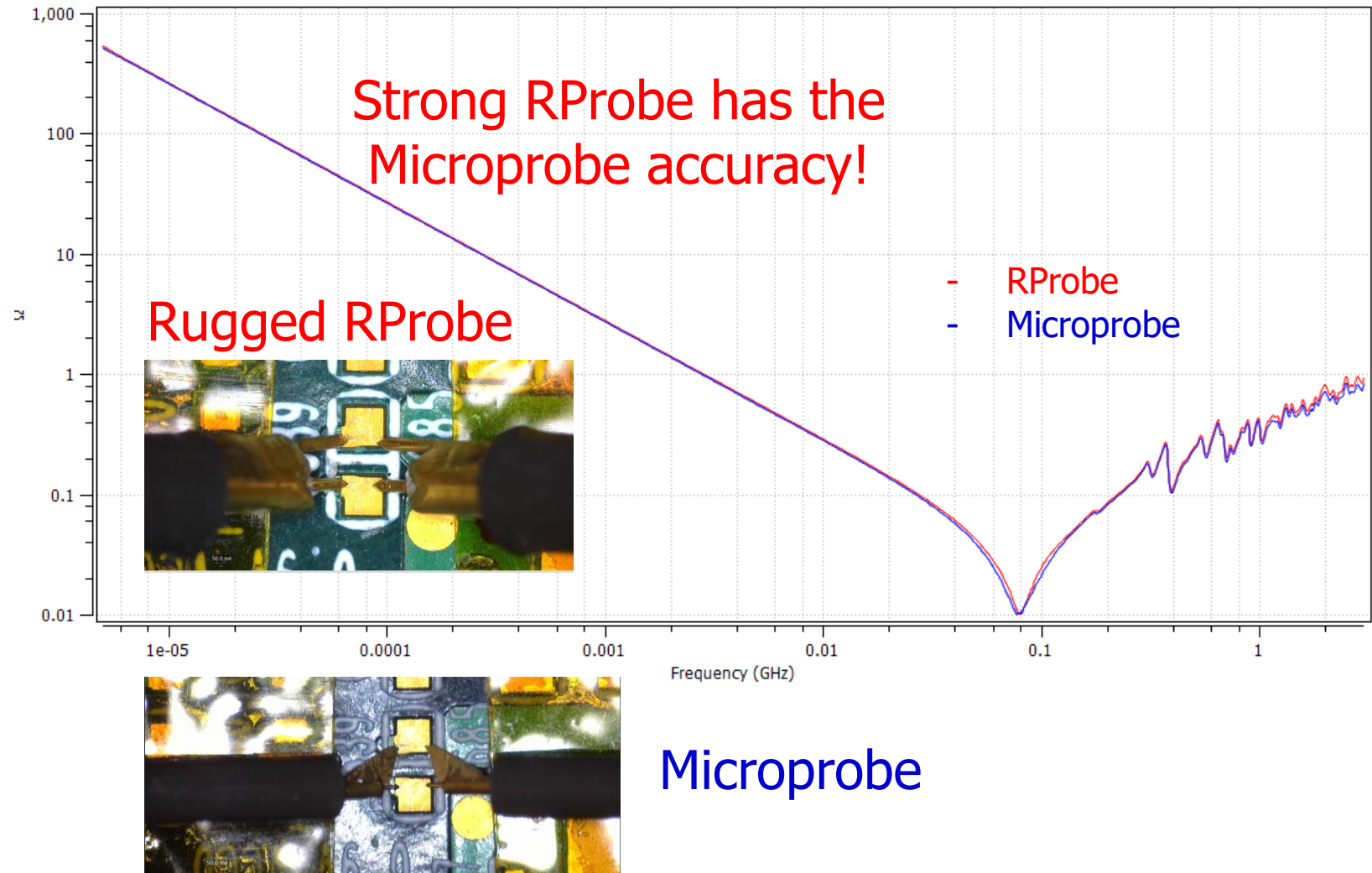


- Measure impedance of 0.9 V core voltage
- Probe on C639 and C644

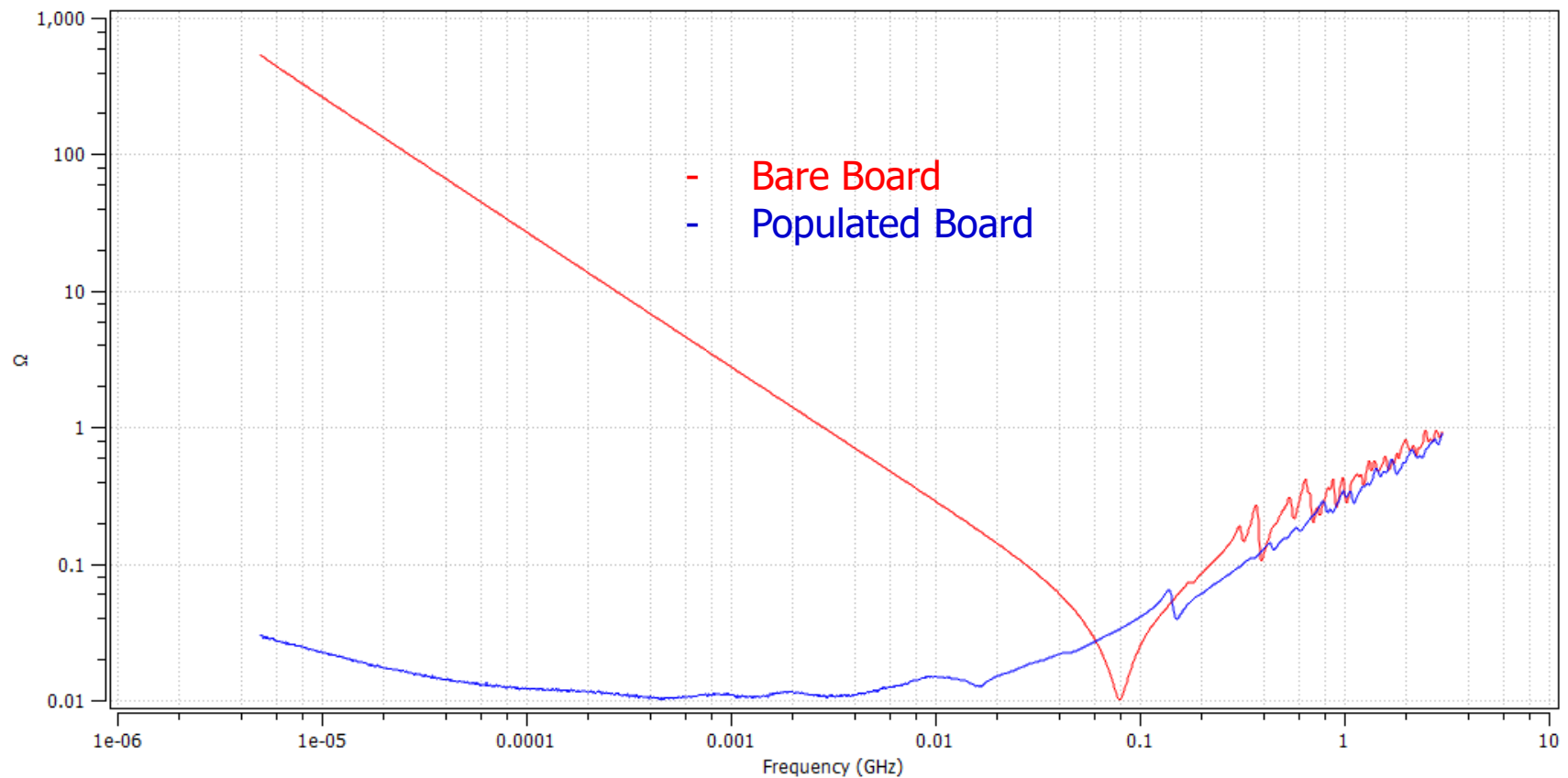




# R-Probe & Microprobe Comparison



# Impedance Between Bare and Populated Boards

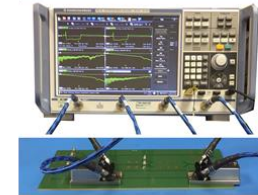
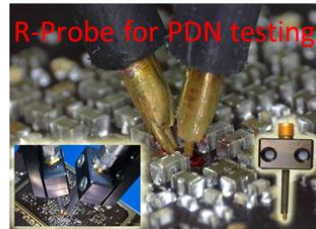
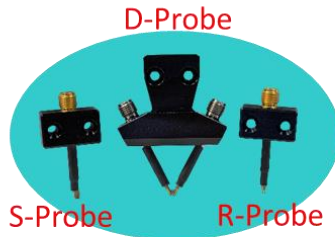


# References

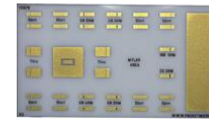
- Istvan Novak, “Power Integrity: Advanced Design and Characterization”  
(<http://www.cei.se/media/48264/cei%20europe%20course%2056.pdf>)
- Istvan Novak, “Measuring Milliohms and Pico Henrys in Power Distribution Networks”  
([http://electrical-integrity.com/Paper\\_download\\_files/DC00\\_MeasuringMiliohms\\_slides.pdf](http://electrical-integrity.com/Paper_download_files/DC00_MeasuringMiliohms_slides.pdf))
- Istvan Novak, “PDN Measurements: Reducing Cable-Braid Loop Error”  
([http://www.electrical-integrity.com/Quietpower\\_files/Quietpower-3.pdf](http://www.electrical-integrity.com/Quietpower_files/Quietpower-3.pdf))



# PacketMicro Product Offering



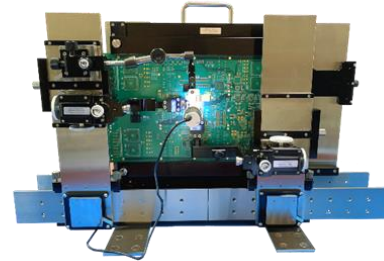
Delta-L 4.0 Solution



TCS70  
Cal Substrate



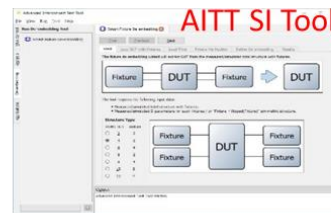
VPS10 2-Sided Probe Station



Flex Positioners



USB Type-C Fixtures HPS24 Probe Station



Slim Phase Stable Cable  
Up to 67 GHz Junkosha MWX161



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- CSS AITT Signal-Integrity Tool
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